



## **MEDIA ALERT**

**MARCH 3, 2010**

### **AKI FUJIMURA TO DELIVER KEYNOTE SPEECH DURING PLENARY SESSION AT ISQED 2010**

#### ***Speech to Cover how Design for E-beam Enables More Designs and Advanced Node Adoption***

The eBeam Initiative, a forum dedicated to the education and promotion of a new design-to-manufacturing approach known as design for e-beam (DFEB), today announced that Aki Fujimura, CEO of D2S and managing sponsor of the Initiative, will deliver a keynote speech at the 11<sup>th</sup> International Symposium on Quality Electronic Design (ISQED) on Wednesday, March 24, 2010 at the DoubleTree Hotel in San Jose, Calif. The speech will be delivered during Plenary Session 2P from 9:15 a.m. to 9:45 a.m. in the Fir/Oak room and will cover “Design for E-beam: Getting the Best Wafers without the Exploding Mask Cost.”

Currently, mask production costs represent a significant proportion of overall lithography cost of ownership—a trend that continues to rise with each new design node. By enabling a decrease in mask costs for semiconductor devices, DFEB is expected to ultimately result in an increased number of design starts and adoption of advanced nodes for a wide range of semiconductor devices. The speech will discuss the reasons behind the rise in mask costs and why it is critically important for designers to understand design for e-beam.

Aki Fujimura’s keynote presentation will be made available online after March 24 at [www.ebeam.org](http://www.ebeam.org).

#### **About The eBeam Initiative**

The eBeam Initiative provides a forum for educational and promotional activities regarding a new design-to-manufacturing approach, known as design for e-beam (DFEB). DFEB reduces mask costs for semiconductor devices by combining design, design software, manufacturing, manufacturing equipment and manufacturing software expertise. The goals of the Initiative are to reduce the barriers to adoption to enable more integrated circuit (IC) design starts and faster time-to-market while increasing the investment in DFEB throughout the semiconductor ecosystem. Members and advisors, which span the semiconductor ecosystem, include: Advantest, Alchip Technologies, Altos Design Automation, Cadence Design Systems, CEA/Leti, D2S, Dai Nippon Printing, Martin M. Deneroff, e-Shuttle, Jack Harding from eSilicon Corporation, Fastrack Design, Fujitsu Microelectronics, GenISys GmbH, GLOBALFOUNDRIES, JEOL, KLA-Tencor, Magma Design Automation, NuFlare Technology, Petersen Advanced Lithography, Colin Harris from PMC-Sierra, Riko Radojic from Qualcomm, Samsung Electronics, STMicroelectronics, Tela Innovations, Toppan Printing, Virage Logic and Vistec Electron Beam Lithography Group. Membership is open to all companies and institutions throughout the electronics industry. To find out more, please visit [www.ebeam.org](http://www.ebeam.org).

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